



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-06-01
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	FLORIANA SAN BIAGIO	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	IDK7*P106ASW	A	BO2A	2017-06-01
Amount	UoM	Unit type	ST ECOPACK Grade	
130.00	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	8.6x3.9x1.52	14	gull wing	
Comment	Package: K7 SO 14 .15 TO JEDEC MS-012; MDF valid for HCF40106YM013TR			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	IDK7*P106ASW			500001.0	999999.0	
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.352	mg	supplier	die	Silicon (Si)	7440-21-3		1.314	mg	971893	10108
				supplier	metallization	Aluminium (Al)	7429-90-5		0.006	mg	4438	46
				supplier	Passivation	Silicon Oxide	7631-86-9		0.012	mg	8876	92
				supplier	polymer die coating	PIX1 Polyimide	108-65-6		0.020	mg	14793	154
Leadframe	Copper & its alloys	37.244	mg	supplier	alloy	Copper (Cu)	7440-50-8		35.999	mg	966572	276915
				supplier	alloy	Iron (Fe)	7439-89-6		0.847	mg	22742	6515
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.051	mg	1369	392
				supplier	alloy	Zinc (Zn)	7440-66-6		0.044	mg	1181	338
				supplier	metallization	Nickel (Ni)	7440-02-0		0.278	mg	7464	2138
				supplier	metallization	Palladium (Pd)	7440-05-3		0.009	mg	242	69
				supplier	metallization	Gold (Au)	7440-57-5		0.008	mg	215	62
				supplier	metallization	Silver (Ag)	7440-22-4		0.008	mg	215	62
Die attach	Other Organic Materials	0.514	mg	supplier	glue	Silver (Ag)	7440-22-4		0.450	mg	875486	3462
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.026	mg	50584	200
				supplier	glue	Urethane Methacrylate Resin	5888-33-5		0.026	mg	50584	200
				supplier	glue	Acrylate polymer	87320-05-6		0.010	mg	19455	77
				supplier	glue	Epoxy cyclohexylethyltrimethoxysilane	3388-04-3		0.001	mg	1946	8
				supplier	glue	tert-Butyl peroxy(2-ethyl)-hexanoate	3006-82-4		0.001	mg	1946	8
Bonding wires	Other inorganic materials	0.114	mg	supplier	wire	Copper (Cu)	7440-50-8		0.114	mg	1000000	877
Encapsulation	Other Organic Materials	90.776	mg	supplier	mold compound	Silica, vitreous	60676-86-0		78.612	mg	866000	604708
				supplier	mold compound	Epoxy Resin	25068-38-6		6.808	mg	74998	52369
				supplier	mold compound	Phenol Resin	29690-82-2		4.539	mg	50002	34915
				supplier	mold compound	Carbon black	1333-86-4		0.454	mg	5001	3492
				supplier	mold compound	Bismuth compound	7440-69-9		0.363	mg	3999	2792